



DOCKET NO.: IND10320

UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT(S) Pennaz, et al. GROUP ART UNIT: 2827  
APPLN. NO.: 09/532,807 EXAMINER: Cuneo, Kamand  
FILED: 3/21/00  
TITLE: CIRCUIT CHIP CONNECTOR AND METHOD OF CONNECTING A  
CIRCUIT CHIP

Certificate of Mailing

Date of deposit: November 20, 2002

I hereby certify that this paper is being deposited with the United States Postal Service on the date indicated above, as first-class mail, with sufficient postage attached thereto, in an envelope addressed to the Assistant Commissioner for Patents, Washington, D.C.

  
\_\_\_\_\_  
Signature of Person Mailing Paper

Sheila Mangerino  
\_\_\_\_\_  
Printed Name of Person Mailing Paper

03/10/2003 INCHILLA 00000001 134772 - 09532807

01 FC:1202

18.00 CH

AMENDMENT

Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

Responsive to the Office Action dated 7/31/02, Paper No. 6, and Examiner's comments with regard thereto, please enter the following amendments in the above-entitled application, without prejudice or disclaimer.

A Petition for Extension of Time to respond, with fee authorization, is submitted concurrently herewith.

IN THE SPECIFICATION:

Please amend the paragraph starting on Page 8, line 9, and ending on line 16 as follows:

With the disclosed interposer, an IC is not directly mechanically and electrically attached to the antenna. The IC is attached to an interposer so that it can be positioned at the connection ends of the antenna circuit. The interposer comprises a base substrate film with two printed pads. An IC is connected between the two electrically isolated pads. The interposer can provide